



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# DB2S314

## Silicon epitaxial planar type

For high speed switching circuits  
DB2J314 in SSMini2 type package

### ■ Features

- Small reverse current  $I_R$
- Short reverse recovery time  $t_{rr}$
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

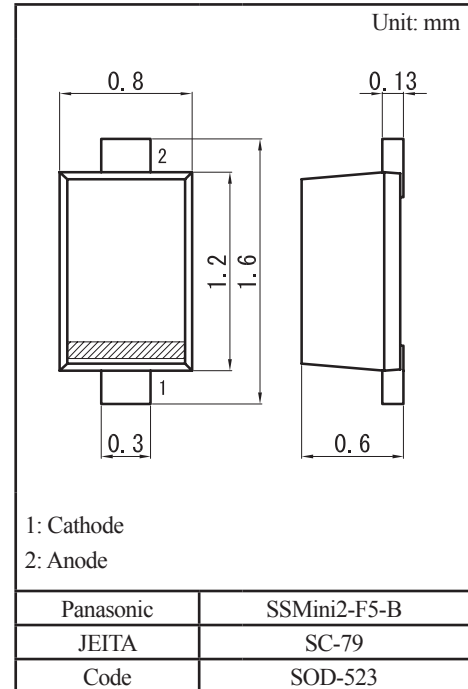
### ■ Marking Symbol: C6

### ■ Packaging

DB2S31400L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Maximum peak reverse voltage	$V_{RM}$	30	V
Forward current	$I_F$	30	mA
Peak forward current	$I_{FM}$	150	mA
Junction temperature	$T_j$	125	$^\circ\text{C}$
Operating ambient temperature	$T_{opr}$	-40 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +125	$^\circ\text{C}$



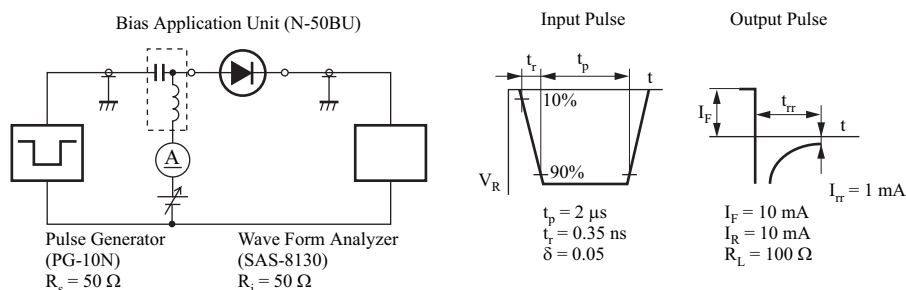
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

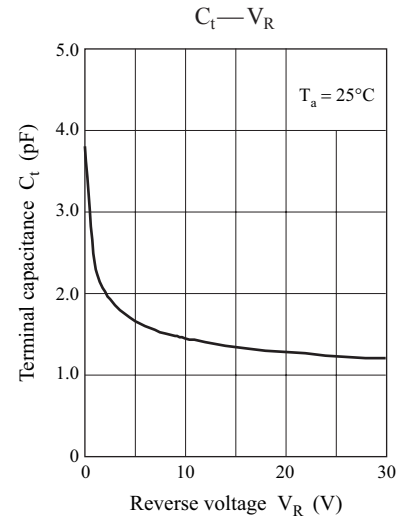
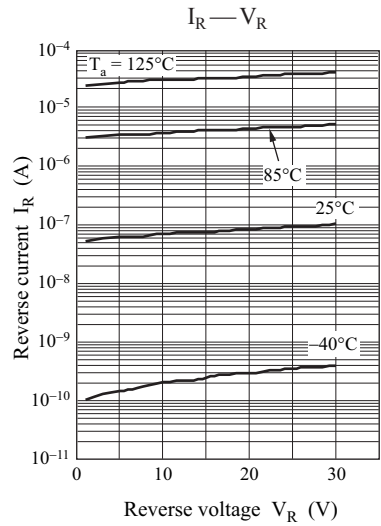
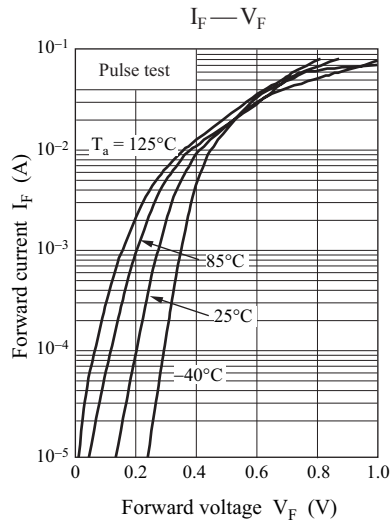
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 1 \text{ mA}$			0.4	V
	$V_{F2}$	$I_F = 30 \text{ mA}$			1.0	
Reverse current	$I_R$	$V_R = 30 \text{ V}$			300	nA
Terminal capacitance	$C_t$	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		1.5		pF
Reverse recovery time *1	$t_{rr}$	$I_F = I_R = 10 \text{ mA}, I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$		1.0		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 2 GHz

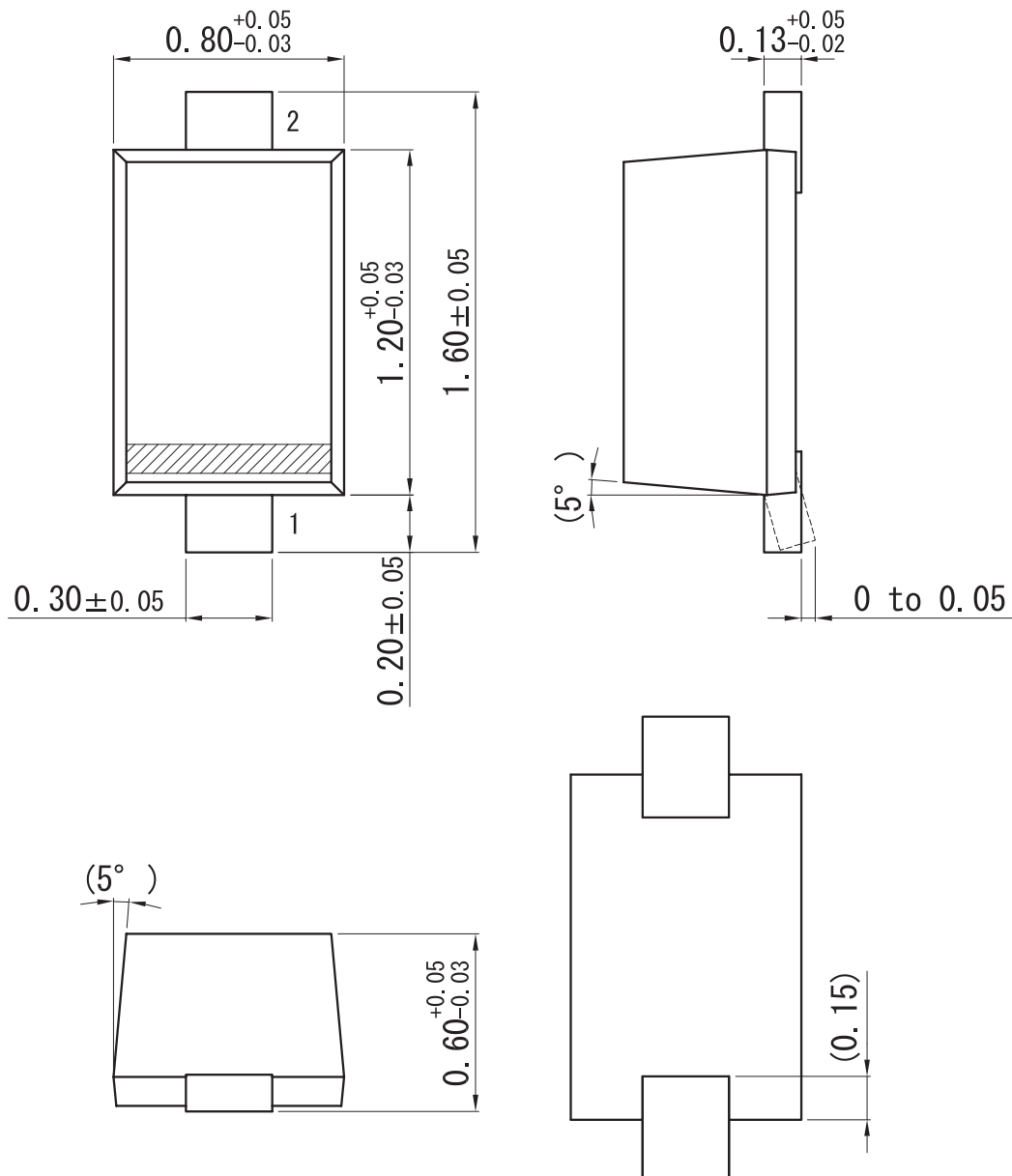
\*1:  $t_{rr}$  measurement circuit



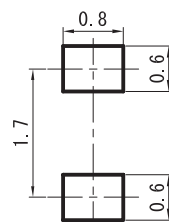


SSMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)





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